

Response and Preliminary Amendment
U.S. Appln. No. 09/685,771

12. (Amended) The substrate as claims in claim 11, further comprising:
a conductive element which electronically connects said top main surface and said
bottom main surface.

D 9 ~~13~~ (Amended) The substrate as claimed in claim ~~11~~^{10 8}, further comprising:
vias which electronically connects said top main surface and said bottom main
surface.

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10 ~~14~~ (Amended) The substrate as claimed in claim ~~13~~⁹, wherein said vias are provided on
the side portion of said substrate.

D 11 ~~15~~ (Amended) The substrate as claimed in claim ~~14~~^{10 8}, wherein said surface layers further
include a side layer which electronically connects said top main surface and said bottom main
surface.

12 ~~16~~ (Amended) The substrate as claimed in claim ~~15~~⁸, wherein said surface layers include
six surface layers.

13 ~~17~~ (Amended) The substrate as claimed in claim ~~16~~⁸, further comprising a signal layer
which is provided between said top main surface and said bottom main surface, and has a pattern
which is connected to said part of circuit.

14 ~~18~~ (Amended) The substrate as claimed in claim ~~17~~⁸, wherein an interval between
said part of circuit and said surface layer is defined to prevent said part of circuit from short-
circuiting.